

## Appendix 3 Product End-of-Life Disassembly instructions

### **Product Identification:**

Marketing Name / Model	Description
HP LP2465 Flat Panel Monitor	LCD Flat Panel Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

### 1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product, which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	6
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		6
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants	Declaration limited to case plastics only.	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0



# 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)		
Screw driver	#2		
Hexagonal inserted handle box wrench			
Pliers			

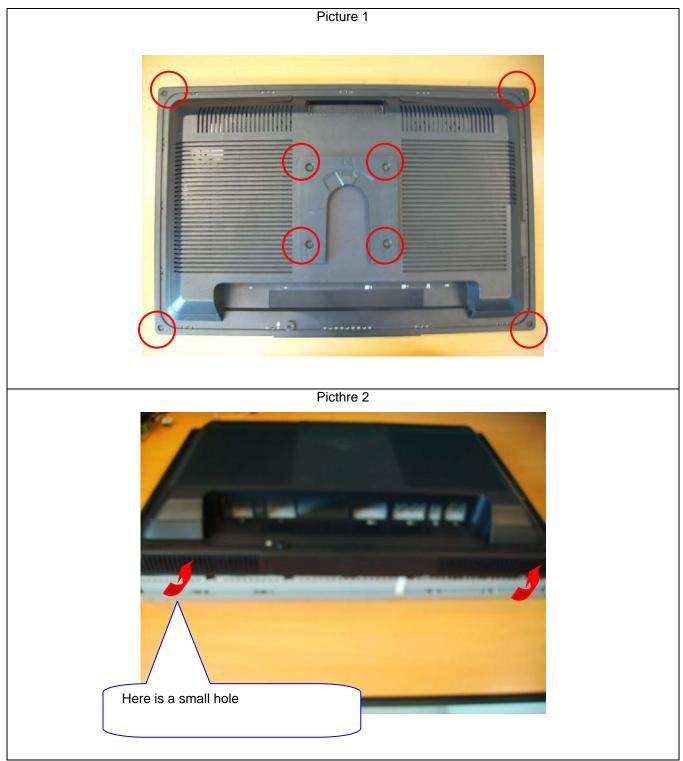
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Remove 8 Base Screws in the back of the monitor units (refer to picture 1)				
2	To insert a screwdriver into two holes. Then disassemble the rear cover form the bezel (refer to picture 2).				
3	Remove all screws which were fixed on main bracket and bezel by screw driver and hexagonal inserted handle box wrench (refer to picture 3, picture 4)				
4	Raise main shielding				
5	Remove all screws which were fixed on all PCBs by screw driver and then disassembly all PCBs by Pliers (refer to picture 5)				
6	Remove all screw which were fixed on panel by screw driver and then remove main bracket which were cover on panel (refer to picture 6)				
7	Remove mercury backlights for selective treatment.				

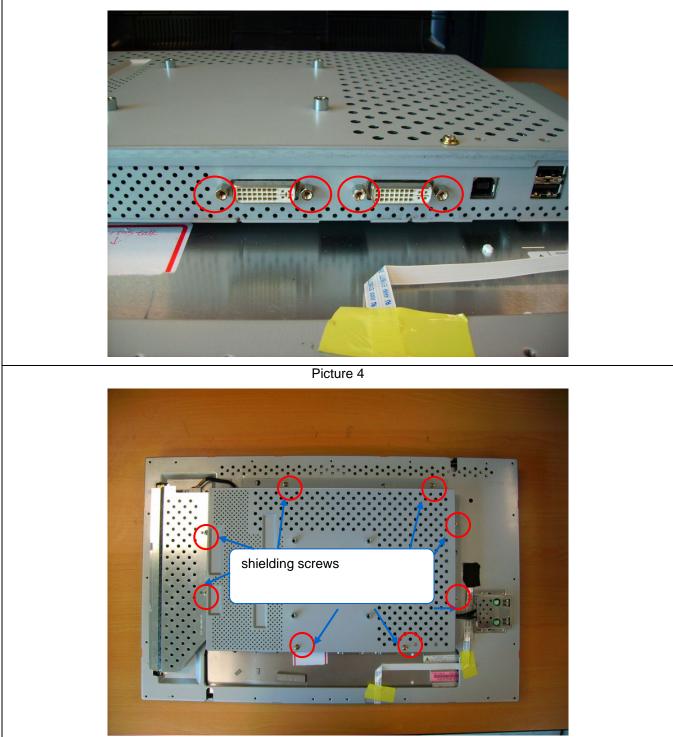


3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:



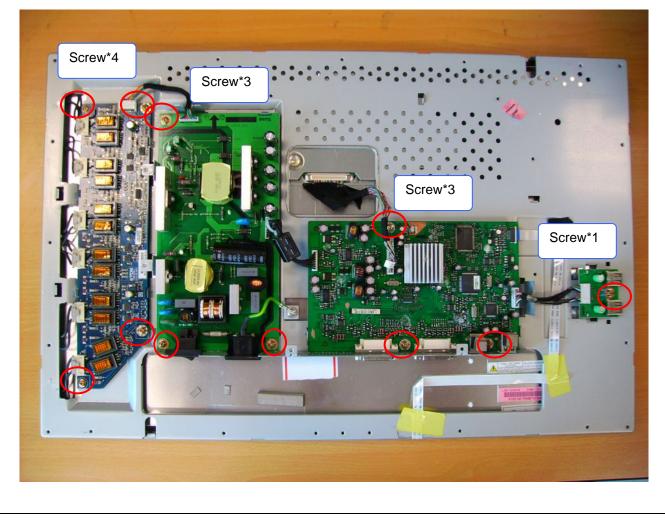


Picture 3





Picture 5





Picture 6 Screw\*2 8 **m** . 10 Screw\*2 0

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Designation	Power BD	Interface BD	Inverter BD	USB BD
Capacitors	C715 C717 C712 C714 C713 C615 C618 C617 C601 C603 C604 C622 C607 C606 C611	C15 C171 C26 C3 C16 C17 C5 C4 C27 C28 C207 C172 C95 C45 C79 C72 C54 C11 C83 C67 C76 C47 C93 C264 C44 C269 C256 C43 C244 C37 C36	C1 C3 C101	C1 C2 C3 C4
Electrolytic Capacitors (larger than 2.5cm)	C605	N/A	N/A	N/A

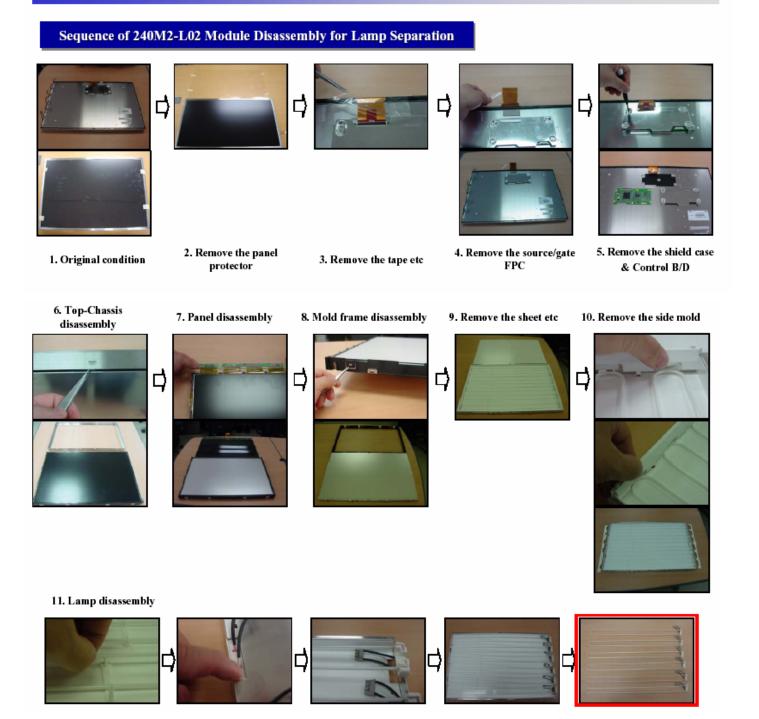


Procedures for panel lamp removal

Refer to picture 7

# 240M2-L02 Lamp Disassembly method

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Picture 7